

# EH4600ETTS-30.720M

|  |  |  |   |
|--|--|--|---|
|  <p><b>Lead Free</b><br/>COMPLIANT</p> |  <p><b>EU RoHS</b><br/>2011/65 +<br/>2015/863<br/>COMPLIANT</p> |  <p><b>China RoHS</b><br/>COMPLIANT</p> |  <p><b>REACH</b><br/>SVHC 163<br/>Jun 15, 2015<br/>COMPLIANT</p> |
|--|--|--|---|



## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 4 Pad 2.5mm x 3.2mm Ceramic Surface Mount (SMD) 30.720MHz  $\pm$ 100ppm -40°C to +85°C

## ELECTRICAL SPECIFICATIONS

|  |   |
|--|---|
| <b>Nominal Frequency</b>                     | 30.720MHz   |
| <b>Frequency Tolerance/Stability</b>         | $\pm$ 100ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°, 260°C Reflow, Shock, and Vibration) |
| <b>Aging at 25°C</b>                         | $\pm$ 5ppm/Year Maximum   |
| <b>Operating Temperature Range</b>           | -40°C to +85°C  |
| <b>Supply Voltage</b>                        | 3.3Vdc $\pm$ 5%   |
| <b>Input Current</b>                         | 12mA Maximum (No Load)  |
| <b>Output Voltage Logic High (Voh)</b>       | 90% of Vdd Minimum (IOH = -8mA)   |
| <b>Output Voltage Logic Low (Vol)</b>        | 10% of Vdd Maximum (IOL = +8mA)   |
| <b>Rise/Fall Time</b>                        | 6nSec Maximum (Measured at 20% to 80% of waveform)  |
| <b>Duty Cycle</b>                            | 50 $\pm$ 10(%) (Measured at 50% of waveform)  |
| <b>Load Drive Capability</b>                 | 30pF Maximum  |
| <b>Output Logic Type</b>                     | CMOS  |
| <b>Pin 1 Connection</b>                      | Tri-State (High Impedance)  |
| <b>Tri-State Input Voltage (Vih and Vil)</b> | 90% of Vdd Minimum or No Connect to Enable Output, 10% of Vdd Maximum to Disable Output (High Impedance)  |
| <b>Standby Current</b>                       | 10 $\mu$ A Maximum (Pin 1 = Ground)   |
| <b>RMS Phase Jitter</b>                      | 20pSec Typical, 30pSec Maximum (Fj = 12kHz to 20MHz)  |
| <b>Period Jitter (RMS)</b>                   | 10pSec Typical  |
| <b>Period Jitter (pk-pk)</b>                 | 60pSec Typical, 100pSec Maximum   |
| <b>Start Up Time</b>                         | 10mSec Maximum  |
| <b>Storage Temperature Range</b>             | -55°C to +125°C   |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                                     |   |
|-------------------------------------|---|
| <b>ESD Susceptibility</b>           | MIL-STD-883, Method 3015, Class 1, HBM: 1500Vdc |
| <b>Fine Leak Test</b>               | MIL-STD-883, Method 1014, Condition A           |
| <b>Flammability</b>                 | UL94-V0   |
| <b>Gross Leak Test</b>              | MIL-STD-883, Method 1014, Condition C           |
| <b>Mechanical Shock</b>             | MIL-STD-883, Method 2002, Condition B           |
| <b>Moisture Resistance</b>          | MIL-STD-883, Method 1004                        |
| <b>Moisture Sensitivity</b>         | J-STD-020, MSL 1                                |
| <b>Resistance to Soldering Heat</b> | MIL-STD-202, Method 210, Condition K            |
| <b>Resistance to Solvents</b>       | MIL-STD-202, Method 215                         |
| <b>Solderability</b>                | MIL-STD-883, Method 2003                        |
| <b>Temperature Cycling</b>          | MIL-STD-883, Method 1010, Condition B           |
| <b>Vibration</b>                    | MIL-STD-883, Method 2007, Condition A           |

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## MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION     |
|-----|----------------|
| 1   | Tri-State      |
| 2   | Case Ground    |
| 3   | Output         |
| 4   | Supply Voltage |

| LINE | MARKING   |
|------|---|
| 1    | <b>E30.720</b><br>E=Ecliptek Designator                 |
| 2    | <b>XXXXX</b><br>XXXXX=Ecliptek Manufacturing Identifier |

## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

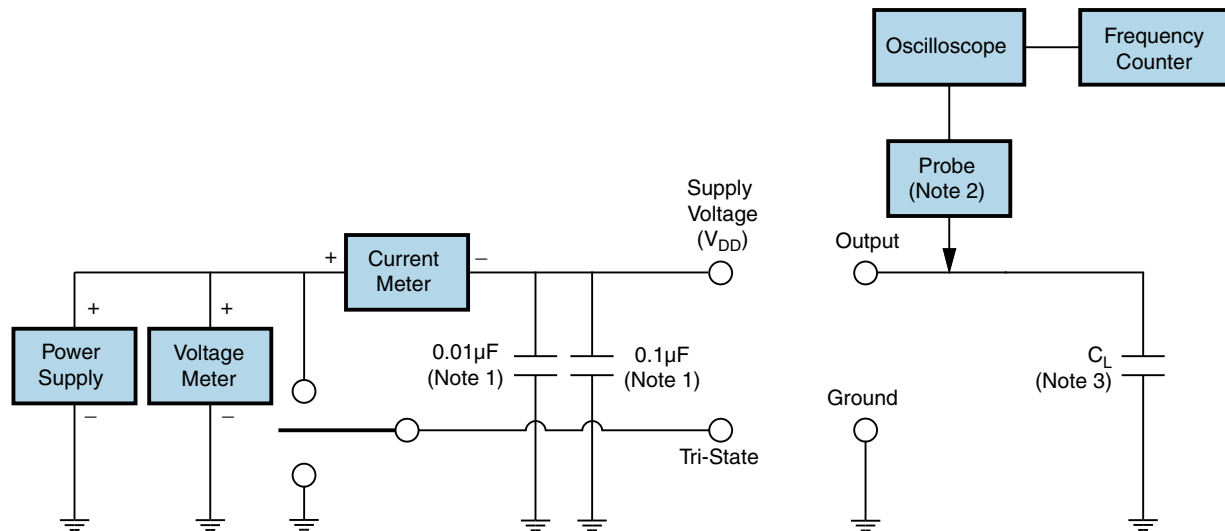
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## OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

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## Recommended Solder Reflow Methods



## High Temperature Infrared/Convection

|  |   |
|--|---|
| <b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b> | 3°C/Second Maximum                                |
| <b>Preheat</b>   |   |
| - Temperature Minimum ( $T_S$ MIN)                             | 150°C   |
| - Temperature Typical ( $T_S$ TYP)                             | 175°C   |
| - Temperature Maximum ( $T_S$ MAX)                             | 200°C   |
| - Time ( $t_s$ MIN)  | 60 - 180 Seconds                                  |
| <b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>     | 3°C/Second Maximum                                |
| <b>Time Maintained Above:</b>                                  |   |
| - Temperature ( $T_L$ )  | 217°C   |
| - Time ( $t_L$ )   | 60 - 150 Seconds                                  |
| <b>Peak Temperature (<math>T_P</math>)</b>                     | 260°C Maximum for 10 Seconds Maximum              |
| <b>Target Peak Temperature (<math>T_P</math> Target)</b>       | 250°C +0/-5°C                                     |
| <b>Time within 5°C of actual peak (<math>t_p</math>)</b>       | 20 - 40 Seconds                                   |
| <b>Ramp-down Rate</b>  | 6°C/Second Maximum                                |
| <b>Time 25°C to Peak Temperature (t)</b>                       | 8 Minutes Maximum                                 |
| <b>Moisture Sensitivity Level</b>                              | Level 1   |
| <b>Additional Notes</b>  | Temperatures shown are applied to body of device. |

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

Ts MAX to TL (Ramp-up Rate) 5°C/Second Maximum

#### Preheat

- Temperature Minimum (Ts MIN) N/A  
 - Temperature Typical (Ts TYP) 150°C  
 - Temperature Maximum (Ts MAX) N/A  
 - Time (ts MIN) 60 - 120 Seconds

Ramp-up Rate (TL to TP) 5°C/Second Maximum

#### Time Maintained Above:

- Temperature (TL) 150°C  
 - Time (tL) 200 Seconds Maximum

Peak Temperature (TP) 240°C Maximum

Target Peak Temperature (TP Target) 240°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak (tp) 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

Ramp-down Rate 5°C/Second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Additional Notes Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

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